



Artificial Intelligence-Based Structural Health Monitoring

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Message from the Guest Editor

The focus of these Special Issues is on the achievements made by combining Structural Health Monitoring and Artificial Intelligence techniques. We invite academic researchers and civil engineering specialists to contribute original research articles which discuss issues related, but not limited to, Structural Health Monitoring, AI-based Automated Diagnosis, Internet of Things, Machine Learning, Deep Learning, Data Mining, Smart Structure.

Keywords

- Structural Health Monitoring
- AI-based Automated Diagnosis
- Internet of Things
- Machine Learning
- Deep Learning
- Data Mining
- Smart Structure





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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